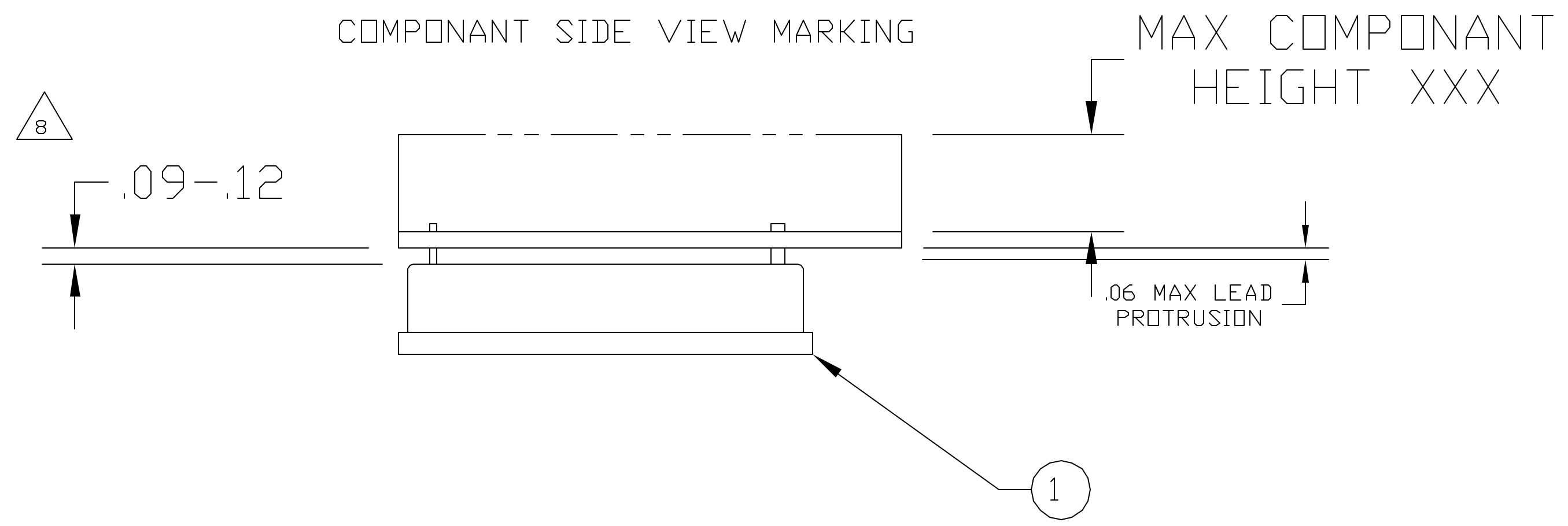
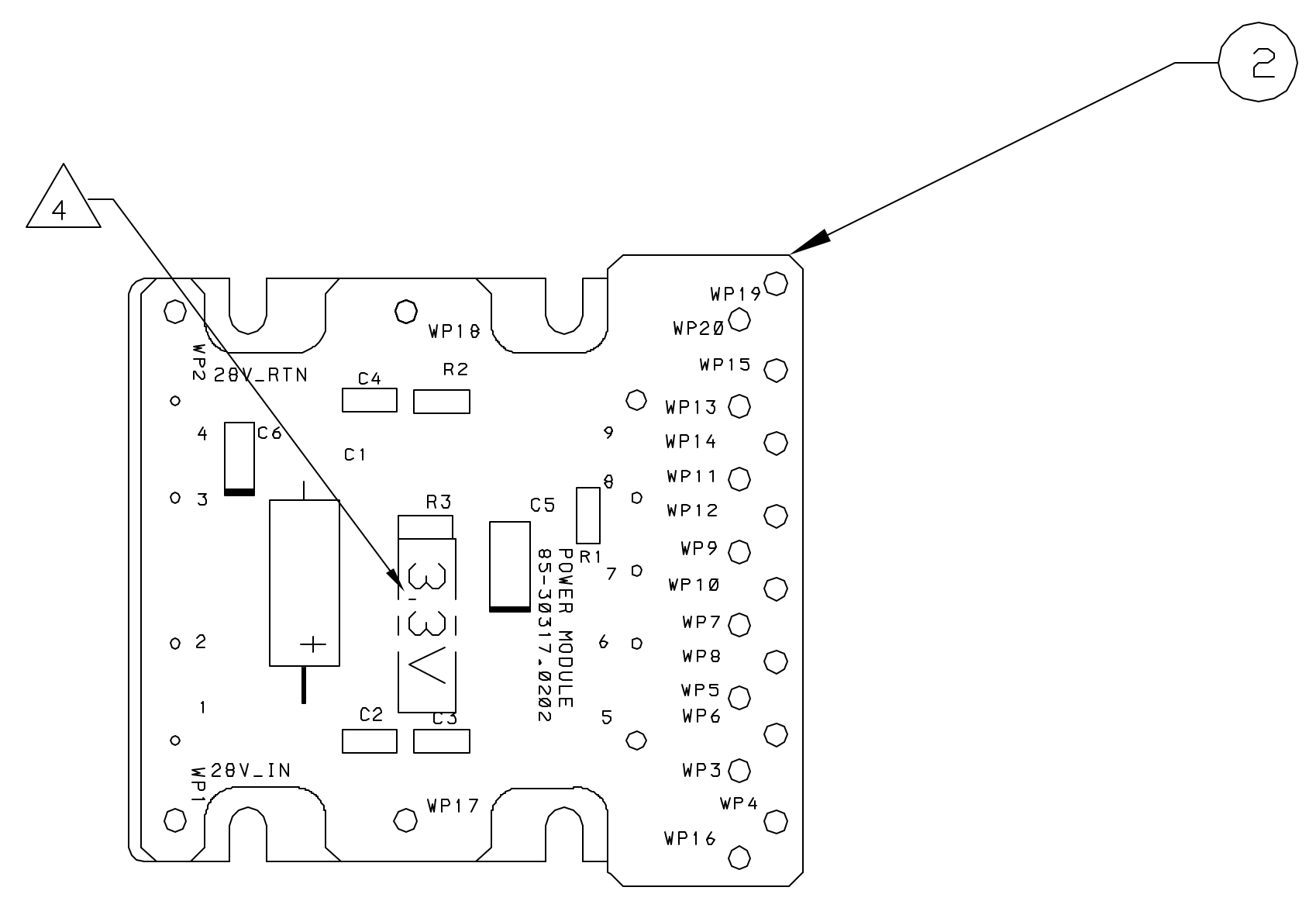


REVISIONS					
EDD	REV	DESCRIPTION	CHECKED	APPROVED	DATE
85-113	01	INITIAL RELEASE			



- NOTES:
- REFER TO MIT DRAWING 85-\_\_\_\_\_ FOR SCHEMATIC
  - FABRICATE IAW NASA SPEC NHB5300.4(3G)
  - SOLDER IAW NASA SPECIFICATION NAS-STD-8739.2 AND NAS-STD-8739.3.
  - MARK VOLTAGE SHOWN USING F/N 5.
  - SEQUENCE OF ASSEMBLY:
    - SOLDER COMPONENTS F/N XXX TO F/N 2, PWB. CLEAN AND CONFORMAL COAT BOTTOM SIDE OF COMPONENT LEADS. DO NOT GET CONFORMAL COAT ON WIRE PADS(EITHER SIDE). (THIS STEP IS TO BE COMPLETED PRIOR TO F/N 1 BEING SOLDERED TO F/N 2.) MASK WIRE PADS AS REQUIRED.
    - SOLDER F/N 2, PWB TO F/N 1. ENSURE PROPER HEIGHT PRIOR TO SOLDERING. CLEAN AND CONFORMAL COAT BOTTOM SIDE OF COMPONENT LEADS. DO NOT GET CONFORMAL COAT ON WIRE PADS(EITHER SIDE). (THIS STEP IS TO BE COMPLETED PRIOR TO ANY WIRES BEING SOLDERED TO F/N 2.) MASK WIRE PADS AS REQUIRED.
    - SOLDER WIRES TO WIRE PADS ON F/N 2, PWB, PER SCHEMATIC AND ASSEMBLY DRAWING. CLEAN AND CONFORMAL COAT TOP AND BOTTOM SIDE.
  - BAG AND TAG ASSEMBLY WITH PART NUMBER AND REVISION.
  - CONFORMAL COAT USING F/N 3.
    - CURE AT 25C, AMBIENT PRESSURE FOR 8 HOURS.
    - REMOVE MASKING AND MASKING RESIDUE PRIOR TO BAKE.
    - VACUUM BAKE AT 65C, 10-4 TORR FOR 24 HOURS.
  - RAISE F/N 1 OFF F/N 2 BY .09-.12 PRIOR TO SOLDERING PINS ON F/N 2 TO F/N 1.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCE: ANGLES +/- 1° 3 PLACE DECIMALS +/- .005 2 PLACE DECIMALS +/- .01		NAME	DATE	Massachusetts Institute of Technology Center for Space Research VOILA	
85-30317	VOILA	DRAWN	M. SMITH	2/24/04	ASSEMBLY 3.3V POWER MODULE
NEXT ASSEMBLY	USED ON	CHECKED			
		APPROVED			
		RELEASED			
APPLICATION		MATERIAL	N/A	FINISH	
		SIZE	D	FSCM NO.	80230
		DWG NO.	30-30317.05		REV
		SCALE	1:1		01
			SHEET		1 OF 1